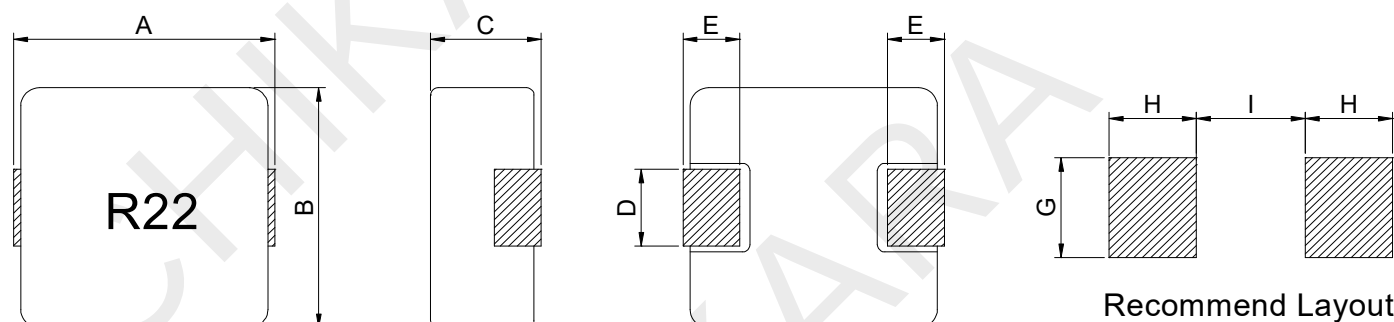


Features

- High energy storage and very low resistance
- Storage temperature range:-55°C to +125°C
- Operating temperature range:-55°C to +125°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:500pcs. Per 13-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



A	B	C	D	E	G	H	I
11.1±0.4	10±0.3	4.0Max.	3.0±0.5	2.0±0.5	4.1	4.1	5.4

Part Number Description

SP14 - 115040 R22 M
① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic

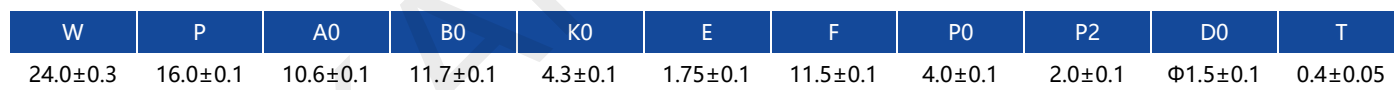


Electrical Characteristic

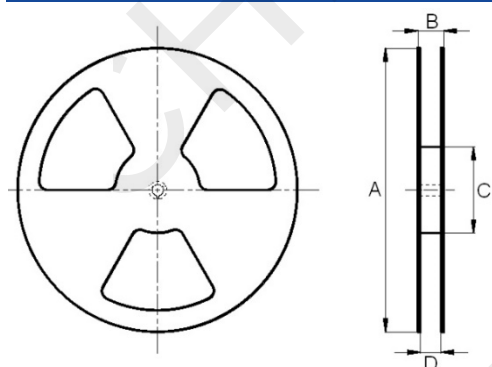
Part Number	Inductance L0(uH)	DCR (mΩ)Typ.	DCR (mΩ)Max.	SRF (MHz)Typ.	Isat (A)Typ.	Irms (A)Typ.
SP14-115040R22M	0.22±20%	0.7	1.0	150	55.0	38.0
SP14-115040R33M	0.33±20%	0.9	1.2	130	45.0	32.0
SP14-115040R36M	0.36±20%	1.0	1.2	120	45.0	30.0
SP14-115040R47M	0.47±20%	1.3	1.7	115	40.0	28.0
SP14-115040R56M	0.56±20%	1.5	1.8	108	33.0	25.0
SP14-115040R68M	0.68±20%	1.9	2.4	75	30.0	23.0
SP14-115040R10M	1.0±20%	2.5	3.3	50	28.0	20.0
SP14-115040R15M	1.5±20%	3.8	4.2	35	24.0	16.0
SP14-115040R22M	2.2±20%	6.0	7.0	30	17.0	12.0
SP14-115040R33M	3.3±20%	10.0	11.8	23	16.0	11.0
SP14-115040R7M	4.7±20%	15.5	20.0	19	14.0	9.0
SP14-115040R8M	6.8±20%	19.5	25.0	15	12.0	8.5
SP14-115040R2M	8.2±20%	23.0	28.0	13	9.0	8.0
SP14-115040R100M	10±20%	26.0	30.0	12	8.5	7.5
SP14-115040R150M	15±20%	38.0	45.0	11	7.0	6.5
SP14-115040R220M	22±20%	55.0	66.0	9.1	5.5	5.0
SP14-115040R330M	33±20%	83.0	92.0	7.3	5.0	4.4
SP14-115040R70M	47±20%	126	145	6.5	3.5	3.3
SP14-115040R80M	68±20%	180	205	5.0	3.0	2.4
SP14-115040R101M	100±20%	295	350	3.8	2.3	2.0

- Test frequency and voltage:100KHz,1Vrms.
- All test data referenced to 25°C ambient.
- Absolute maximum voltage: 50Vdc.
- Saturation current(Isat) will cause L0 to drop approximately 30%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It's suggested to verify the temperature rise of the component under the real operation application conditions.

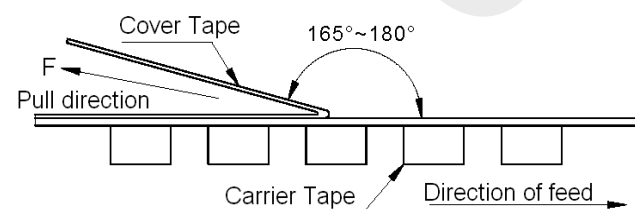
- Carrier Tape (Unit:mm)



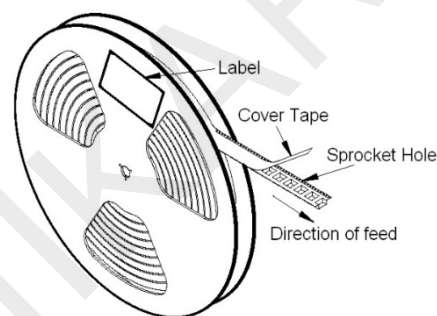
A	B	C	D
$\Phi 330 \pm 1.0$	28.9Max.	$\Phi 100 \pm 1.0$	24.5 ± 0.5



Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.3N	165°~180°	300mm/min.



✖ Packing is referred to the international standard IEC 60286-3.



Parts per reel

500Pcs

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.